



BSI Standards Publication

Dynamic modules

Part 6-5: Design guide — Investigation of operating mechanical shock and vibration tests for dynamic modules

National foreword

This Published Document is the UK implementation of IEC/TR 62343-6-5:2014. It supersedes PD IEC/TR 62343-6-5:2011, which is withdrawn.

The UK participation in its preparation was entrusted by Technical Committee GEL/86, Fibre optics, to Subcommittee GEL/86/3, Fibre optic systems and active devices.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

© The British Standards Institution 2014.
Published by BSI Standards Limited 2014

ISBN 978 0 580 85413 2
ICS 33.180.20

Compliance with a British Standard cannot confer immunity from legal obligations.

This Published Document was published under the authority of the Standards Policy and Strategy Committee on 31 July 2014.

Amendments/corrigenda issued since publication

Date	Text affected
-------------	----------------------



TECHNICAL REPORT



**Dynamic modules –
Part 6-5: Design guide – Investigation of operating mechanical shock and
vibration tests for dynamic modules**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

PRICE CODE

T

ICS 33.180.20

ISBN 978-2-8322-1641-5

Warning! Make sure that you obtained this publication from an authorized distributor.

CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Background	6
3 Questionnaire results in Japan	6
4 Evaluation plan.....	7
5 Evaluation results	7
5.1 Step 1	7
5.1.1 Evaluation of hammer impact.....	7
5.1.2 Evaluation of adjacent board insertion and rack handle impact	9
5.2 Step 2.....	9
5.3 Step 3.....	11
5.3.1 MEMS-VOA	11
5.3.2 WSS and tuneable laser	14
6 Simulation	16
6.1 Simulation model.....	16
6.2 Frequency characteristics	17
6.3 Dependence on PC board design.....	18
6.4 Consistency of evaluation and simulation results	19
7 Summary	19
8 Conclusions.....	20
Annex A (informative) Results of a questionnaire on dynamic module operating shock and vibration test conditions	21
A.1 Background.....	21
A.2 Questionnaire methodology	21
A.3 Survey result.....	21
Bibliography.....	24
Figure 1 – Photos of evaluating hammer impact, rack and boards.....	7
Figure 2 – Evaluation results of hammer impact H	8
Figure 3 – Photos of evaluating adjacent board insertion and rack handle impact	9
Figure 4 – DUT (VOA and WSS) installed on PC boards and rack for second step of the evaluation	10
Figure 5 – Oscilloscope display of waveform changes in vibration and optical output.....	10
Figure 6 – Evaluation results when employing MEMS-VOA for Z-axis	11
Figure 7 – Photos of the MEMS-VOA shock/vibration test equipment.....	12
Figure 8 – Operating shock characteristics of MEMS-VOA	12
Figure 9 – Vibration evaluation results for MEMS-VOA (Z-axis; 2 G).....	13
Figure 10 – Shock and vibration evaluation system for WSS and tuneable laser	14
Figure 11 – Shock evaluation results for WSS (directional dependence)	15
Figure 12 – Shock evaluation results for WSS (z-axis direction and shock dependence).....	15
Figure 13 – Simulation model.....	17
Figure 14 – Vibration simulation results	17
Figure 15 – Vibration simulation results (dependence on board conditions).....	18

Table 1 – Rack and board specifications, conditions of evaluating hammer impact and acquiring data 8

Table 2 – Dynamic modules used in evaluation and evaluation conditions 10

Table 3 – Conditions for MEMS-VOA vibration/shock evaluation 12

Table 4 – Results of MEMS-VOA vibration evaluation 13

Table 5 – Conditions for simulating board shock and vibration 16

Table 6 – Comparison of hammer impact shock evaluation results and vibration simulation (conditions: 1,6 mm × 240 mm × 220 mm, t × H × D) 19

Table A.1 – Summary of survey results on operating shock and vibration test conditions 22

INTERNATIONAL ELECTROTECHNICAL COMMISSION

DYNAMIC MODULES –**Part 6-5: Design guide –
Investigation of operating mechanical shock
and vibration tests for dynamic modules**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC 62343-6-5, which is a technical report, has been prepared by subcommittee 86C: Fibre optic systems and active devices, of IEC technical committee 86: Fibre optics.

This second edition cancels and replaces the first edition published in 2011. It constitutes technical revision.

The main change with respect to the previous edition is the addition of "Results of a questionnaire on dynamic module operating shock and vibration test conditions" in Annex A.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
86C/1206/DTR	86C/1246/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 62343 series, published under the general title *Dynamic modules*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

DYNAMIC MODULES –

Part 6-5: Design guide – Investigation of operating mechanical shock and vibration tests for dynamic modules

1 Scope

This part of IEC 62343, which is a technical report, describes an investigation into operating mechanical shock and vibration for dynamic modules. It also presents the results of a survey on the evaluation and mechanical simulation of mechanical shock and vibration testing. Also included is a study of standardization for operating mechanical shock and vibration test methods.

2 Background

The recent deployment of advanced, highly flexible optical communication networks using ROADMs (*reconfigurable optical add drop multiplexing*) systems has been accompanied by the practical utilization of dynamic wavelength dispersion compensators, wavelength blockers and wavelength selective switches as “dynamic modules.” Since these dynamic modules incorporate such new technology as MEMS (*micro electromechanical systems*), there are concerns about the vulnerability to operating shock and vibration conditions, which urgently require establishing evaluation methods and conditions. Standards for shock and vibration test conditions pertaining to storage and transport are already established, but methods and conditions for evaluating operating shock and vibration are not yet established.

The JIS (*Japanese Industrial Standards*) committee consequently conducted a questionnaire survey on the shock and vibration testing of passive optical components and dynamic modules in commercial use. The survey revealed that many respondents confirmed a need to standardize evaluation conditions for operating shock and vibration; some suggested earthquake, hammer impact testing and inserting an adjacent board as cases of shock and vibration during dynamic module operation. Based on the survey results, the JIS committee evaluated operating shock and vibration by conducting hammer impact tests using several dynamic modules, compared the results through simulation, and then recommended specific evaluation conditions.

This technical report is based on OITDA (Optoelectronic Industry and Technology Development Association) – TP (Technical Paper), TP05/SP_DM-2008, "Investigation on operating vibration and mechanical impact test conditions for optical modules for telecom use."

3 Questionnaire results in Japan

The JIS committee conducted a questionnaire on operating shock and vibration testing. The questionnaire allowed the respondents to specify the optical components to be tested. This questionnaire included optical switches, VOAs (*variable optical attenuators*) and tuneable filters among the mechanical components used in all possible situations. The survey covered 18 organizations: eight Japanese manufacturers of mechanical optical components, eight device makers as users of such components, and two research institutes. Responses were received from 14 of these organizations for a response rate of 78 %, among which 12 respondents specified optical switches, seven specified VOAs and three chose tuneable filters. In tabulating the data, the survey asked questions regarding these three types of components and described occurrences not dependent on the type of component, the manufacturer and the user, and evaluation conditions.